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DERWENT-WEEK: 198625

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TITLE: Rust prevention of printed circuit
substrate - involves applying protective layer to surface,
followed by use of rust inhibitor before removing
protective layer

PATENT-ASSIGNEE: MATSUSHITA ELECTRIC WORKS LTD[MATW]

PRIORITY-DATA: 1984JP-0213428 (October 12, 1984)

PATENT-FAMILY:

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JP 61091998 A		May 10, 1986	N/A
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APPLICATION-DATA:

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ABSTRACTED-PUB-NO: JP 61091998A

BASIC-ABSTRACT:

A protective layer is formed on the surface of the circuit layer of a metal base print substrate, in which a metal plate is used as the base. Then, a rust inhibitor is applied to the metal plate, after which the protective layer is removed.

The rust inhibitor is pref. made from alkali metal silicic acid salt.

USE/ADVANTAGE - Enables the metal plate to be subjected to rust prevention treatment without impairing the soldering properties of the circuit layer. The insulating layer is thus prevented from peeling off the metal plate due to rusting.

In an example, a vinyl chloride sheet provided with adhesive is applied to the surface of the circuit layer of a metal base print substrate. The substrate is dipped in a soln. of potassium silicate as a rust inhibitor. The substrate is withdrawn and the protective layer is removed after 20 mins. of the treatment at 150 deg.C.

CHOSEN-DRAWING: Dwg.1/2

TITLE-TERMS: RUST PREVENT PRINT CIRCUIT SUBSTRATE APPLY
PROTECT LAYER SURFACE
FOLLOW RUST INHIBIT REMOVE PROTECT LAYER

DERWENT-CLASS: L03 M14 P42 V04

CPI-CODES: L03-H04E; M14-K;

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